

# OptoTEC™ OT Series Thermoelectric Cooler

### Note: This product is not recommended for new designs.

This product series has been replaced with the OptoTEC $^{\text{\tiny{TM}}}$  OTX Series. The recommended replacement is:

MFG Part Number: 387006794

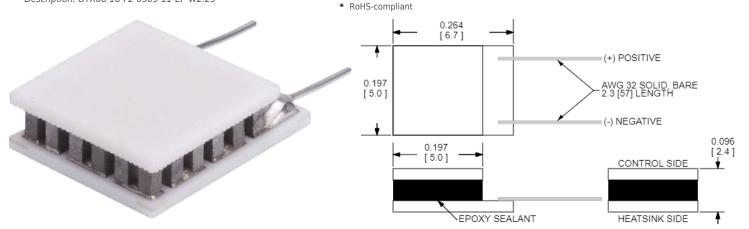
Description: OTX08-18-F2-0505-11-EP-W2.25

#### **Features**

- Miniature geometric sizes
- Precise temperature control
- Reliable solid-state operationNo sound or vibration
- DC operation

#### **Applications**

- Thermoelectric Cooling for CMOS Sensors
- Cooling Solutions for Autonomous Systems
- Heads-Up Displays, Imaging Sensors



CERAMIC MATERIAL: Al<sub>2</sub>O<sub>3</sub>

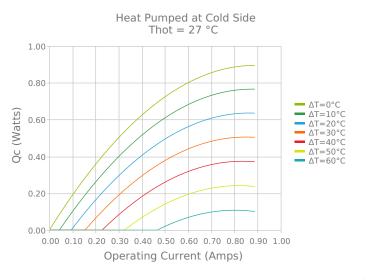
SOLDER CONSTRUCTION: 138°C, BiSn

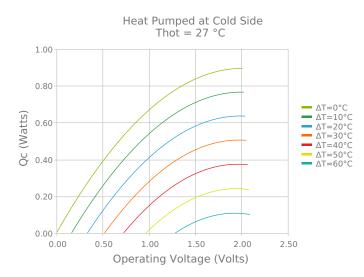
INCHES [ MM ]

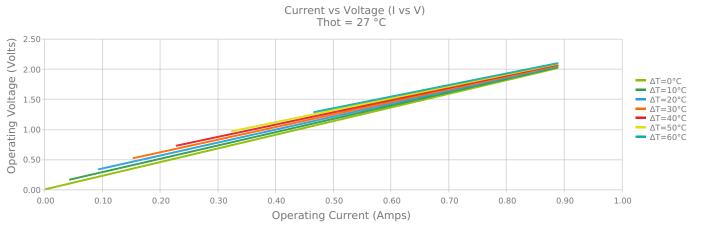
Note: Allow 0.020 in [0.5 mm] around perimeter of the thermoelectric cooler and lead wire attachment to accommodate sealant

### **ELECTRICAL AND THERMAL PERFORMANCE**

For maximum performance, be sure to orient the CONTROL side of the TEC against the application to be managed and the HEATSINK side against the heat sink or other heat rejection method. The CONTROL side is always opposite the side with lead attachments. Lead attachment is a passive heat loss and less impactful if located on the side that attaches to the heat exchanger.

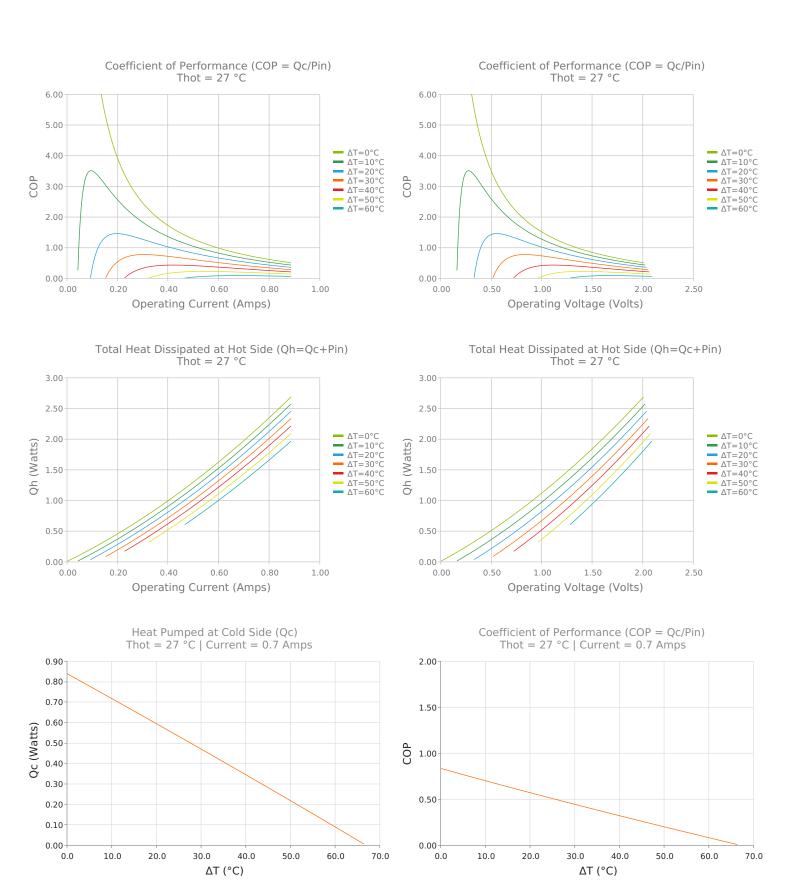








**Legacy Product** 





# **SPECIFICATIONS\***

**Hot Side Temperature** 

 $Qcmax (\Delta T = 0)$ 

 $\Delta T max (Qc = 0)$ 

Imax (I @ ATmax)

Vmax (V @  $\Delta$ Tmax)

**Module Resistance** 

**Max Operating Temperature** 

Weight

27.0 °C	35.0 °C	50.0 °C
0.9 Watts	0.9 Watts	1.0 Watts
68.0°C	70.9°C	76.0°C
0.8 Amps	0.8 Amps	0.8 Amps
1.9 Volts	2.0 Volts	2.1 Volts
2.27 Ohms	2.36 Ohms	2.54 Ohms
80 °C		
1.0 gram(s)		

# **FINISHING OPTIONS**

Suffix	Thickness	Flatness / Parallelism	<b>Hot Face</b>	Cold Face	<b>Lead Length</b>
11	2.438 ±0.127 mm 0.096 ± 0.0050 in	0.051 mm / 0.051 mm 0.002 in / 0.002 in	Lapped	Lapped	50.8 mm 2.00 in

### **SEALING OPTIONS**

Suffix	Sealant	Color	<b>Temp Range</b>	Description
EP	Epoxy	Black	-55 to 150°C	Low density syntactic foam epoxy encapsulant

# **NOTES**

- 1. Max operating temperature: 80°C
- 2. Do not exceed Imax or Vmax when operating module
- 3. Reference assembly guidelines for recommended installation
- 4. Solder tinning also available on metallized ceramics

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<sup>\*</sup> Specifications reflect thermoelectric coefficients updated March 2020